

Intel® Skylake 1U fanless 19" rackmount

Intel® i7-6700TE Processor, graphic card build in supports up to 9 independent display output, 16V to 32V DC-in, extended temp. -20 ~ 60°C



- Intel® Skylake i7-6700TE (4 cores, 3.4GHz)
- 2x SO-DIMM DDR4 up to 32GB
- Graphic AMD E8860/ NVIDIA GTX950M build in
- Rich I/O interface with 4x USB, 2x COM, dual LAN
- 1 x mPCIe expansion slot
- 2x 2.5" HDD/ SSD easy swap tray
- Wide range 16V to 32V DC-in
- Extended operating temperature. -20 to 60°C

Specifications

Specifications	
High Performance Processor	Support LGA1151 Intel® 6th Gen Core™ Skylake-S Processors (Max. Quad-Core, 8 Thread Support, SmartCache, Build-in HD Graphics 500 for excellent 3D, DirectX 12, OpenGL 4.4, OpenCL 2.0, Turbo Boost Technology 2.0 , VPro and Hyper-Threading and Intel® Ready Mode Technology support.
Memory	2 x 256-pin SODIMM, DDR4 / 2133 MHz up to 32GB ECC SDRAM
Chipset	Intel® Q170/H110 Chipset providing integrated USB 3.0 and supporting 6th generation Intel® Core™ processor families
Expansion Slot	1 x Full-size miniPCle with SIM Card for 3.5G connectivity 1 x M.2 (NGFF) 80*22 mm / B+M Key slot, for operating system, Rugged -40/+85°C High Capacity Military-Grade SSD up to 512GB, ONLY the Q170 support. 1 x PCIe16 slot (Gen.3) for High Performance Graphic Card
Display	
Display Port	Resolution up to 3840 x 2160@60 Hz
DVI-I	Resolution up to 2560 x 1600 @ 60Hz
PCIEx16 Graphic Card	Optional
Storage	
HDD/SDD	ROC249A: 2 x 2.5" HDD, w/ RAID 0/1/5/10 support ROC249A1: 2 x 2.5" HDD
M.2	M.2 (NGFF) - up to 512GB Capacity Rugged Industrial NAND Flash M.2 Storage w/ Rugged -40/+85°C High Capacity , optional Pre-loaded with Linux or Windows OS- 64 / 128 / 256 / 512GB Innodisk M.2 (S80) 3MG2-P Series MLC SATA III 6Gb/s Flash SSD, Rated for 520 MB/sec Sequential Read ; 450 MB/sec Write Max Vibration: 20G @7~2000Hz, Shock: 1500G @ 0.5m, MTBF: 3 million hours
Ethernet	
Ethernet	1 x Intel I211AT, 1 x Intel I219LM Gigabit LAN Interfaces (10/100/1000Mbps)
Rear I/O	
DisplayPort	2 x 20Pin External connectors (Female)
DVI-I	1 x 29Pin DVI-I connector (Female)
Ethernet	2 x RJ45 Gigabit Ethernet LAN Interfaces
Audio	2 x 3.5mm Audio Jacks (1 x MIC, 1 x Line-Out)
Serial Port	2 x DB9 connector (RS-232)
USB Port	4 x USB3.0 standard-A connector
DC-IN	1 x 4P Rugged Terminal connector
Front I/O	
Button	1 x Power Button
Indicator LED	Power, HDD
Power Requirement	
Power Input	16V to 32V DC-in, 150W max.
Power Type	AT/ATX Mode Select by Jumper

Applications, Operating System	
Applications	Commercial and Military Platforms Requiring Compliance to MIL-STD-810G Embedded Computing, Process Control, Intelligent Automation and manufacturing applications where Harsh Temperature, Shock, Vibration, Altitude, Dust and EMI Conditions Used in all aspects of the military
Operating System	Microsoft Windows 7 Professional 32/64Bit, Microsoft Windows 8 Professional 32/64Bit, Ubuntu13.04, Ubuntu13.10, Ubuntu14.04, Fedora 20
Physical	
Dimension (W x D x H)	440 x 400 x 44 mm
Weight	6.0 Kg (13.23 lbs)
Chassis	SECC
Heatsink	Aluminum Alloy, Corrosion Resistant
Finish	Anodic aluminum oxide (Color Iron gray)
Cooling	Natural Passive Convection/Conduction. No Moving Parts
Ingress Protection	Dust Proof (Similar to IP54)
Environmental	
MIL-STD-810G Test	Method 507.5, Procedure II (Temperature & Humidity) Method 516.6 Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6 Shock-Procedure I Operating (Mechanical Shock) Method 514.6 Vibration Category 24/Non-Operating (Category 20 & 24, Vibration) Method 514.6 Vibration Category 20/Operating (Category 20 & 24, Vibration) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock)
Reliability	No Moving Parts; Passive Cooling Designed & Manufactured using ISO 9001/2000 Certified Quality Program
EMC	CE and FCC compliance
Green Product	RoHS, WEEE compliance
Operating Temp.	-20° to 60°C(ambient with air flow)
Storage Temp.	-20 to 70°C
Relative Humidity	5% to 95%, non-condensing

Ordering information ►

ROC249A

MIL-STD-810G 19" 1U Rack-mount fanless Rugged System with Intel® Skylake-S, 16V to 32V DC-in, RAID, M.2 (NGFF), Mini PCIe, Extended Temp. -20~60°C

ROC249A1

MIL-STD-810G 19" 1U Rack-mount fanless Rugged System with Intel® Skylake-S, 16V to 32V DC-in, Mini PCIe, Extended Temp. -20~60°C

ROC249A, Intel® Skylake 1U fanless 19" rackmount with Intel® i7-6700TE Processor, graphic card build in supports up to 9 independent display output, 16V to 32V DC-in, extended temp. -20 ~ 60°C

Appearance ▶

Front Side



Back Side

